## ABSTRACT OF THE DISCLOSURE

A MEMS capping method and apparatus uses a cap structure on which is

formed a MEMS cavity, a cut capture cavity, and a cap wall. The cap wall is
essentially the outer wall of the MEMS cavity and the inner wall of the cut
capture cavity. The cap structure is bonded onto a MEMS structure such that the
MEMS cavity covers protected MEMS components. The cap structure is
trimmed by cutting through to the cut capture cavity from the top of the cap
structure without cutting all the way through to the MEMS structure.